

# Silicon Carbide (SiC) MOSFET - 20 mohm, 1200 V, M1, TO-247-4L NVH4L020N120SC1

#### **Features**

- Typ.  $R_{DS(on)} = 20 \text{ m}\Omega$
- Ultra Low Gate Charge (Q<sub>G(tot)</sub> = 220 nC)
- High Speed Switching with Low Capacitance (Coss = 258 pF)
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb–Free 2LI (on second level interconnection)

## **Typical Applications**

- Automotive On Board Charger
- Automotive DC-DC Converter for EV/HEV
- Automotive Traction Inverter

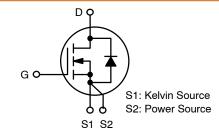
### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	1200	V
Gate-to-Source Voltage	!		$V_{GS}$	-15/+25	٧
Recommended Operation Values of Gate-to-Source Voltage		$V_{GSop}$	-5/+20	>	
Continuous Drain Current (Note 2)	Steady T <sub>C</sub> = 25°C State		I <sub>D</sub>	101	Α
Power Dissipation (Note 2)			$P_{D}$	500	V
Continuous Drain Current (Notes 1, 2)	Steady State	T <sub>C</sub> = 100°C	I <sub>D</sub>	71.4	Α
Power Dissipation (Notes 1, 2)			P <sub>D</sub>	250	W
Pulsed Drain Current (Note 3)	T <sub>A</sub> = 25°C		I <sub>DM</sub>	408	Α
Single Pulse Surge Drain Current Capability	$T_A$ = 25°C, $t_p$ = 10 $\mu$ s, $R_G$ = 4.7 $\Omega$		I <sub>DSC</sub>	807	Α
Operating Junction and Storage Temperature Range		$T_J$ , $T_{stg}$	-55 to +175	ç	
Source Current (Body Diode)			IS	46	Α
Single Pulse Drain-to-Source Avalanche Energy ( $I_{L(pk)} = 23 \text{ A}, L = 1 \text{ mH}$ ) (Note 4)			E <sub>AS</sub>	264	mJ
Maximum Lead Temperature for Soldering (1/8" from case for 5 s)			TL	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- JA is constant value to follow guide table of LV/HV discrete final datasheet generation.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 3. Repetitive rating, limited by max junction temperature.
- 4. EAS of 264 mJ is based on starting  $T_J = 25^{\circ}\dot{C}$ ; L = 1 mH,  $I_{AS} = 23$  A,  $V_{DD} = 120$  V,  $V_{GS} = 18$  V.

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
1200 V	28 mΩ @ 20 V	102 A

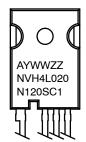


#### **N-CHANNEL MOSFET**



TO-247-4L CASE 340CJ

#### MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week ZZ = Lot Traceability

NVH4L020N120SC1 = Specific Device Code

## **ORDERING INFORMATION**

	Device	Package	Shipping
N'	VH4L020N120SC1	TO-247-4L	30 Units / Tube

Table 1. THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case - Steady State (Note 2)		0.3	°C/W
Junction-to-Ambient - Steady State (Notes 1, 2)		40	

Table 2. ELECTRICAL CHARACTERISTICS (T. J = 25°C unless otherwise specified)

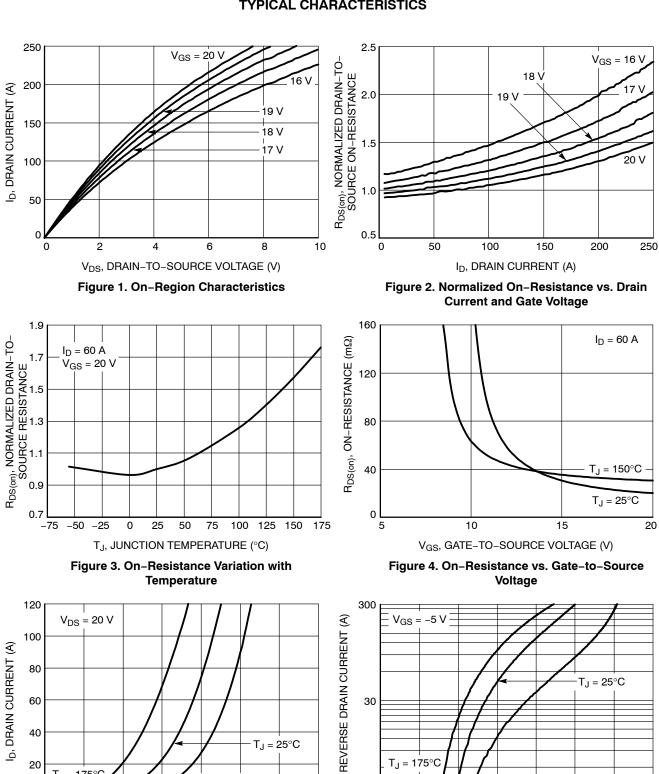
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•	•					
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA		1200	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = 1 mA, referenced to 25°C		-	0.5	-	V/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25°C	-	-	100	μΑ
		V <sub>DS</sub> = 1200 V	T <sub>J</sub> = 175°C	-	_	1	mA
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{GS} = +25/-15 \text{ V}, V_{D}$	os = 0 V	-	_	±1	μΑ
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{D} = 20 \text{ m}$	ıA	1.8	2.7	4.3	V
Recommended Gate Voltage	$V_{GOP}$			-5	-	+20	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 20 V, I <sub>D</sub> = 60 A	, T <sub>J</sub> = 25°C	-	20	28	mΩ
		V <sub>GS</sub> = 20 V, I <sub>D</sub> = 60 A	, T <sub>J</sub> = 175°C	-	37	50	
Forward Transconductance	9FS	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 60 A		-	36	-	S
CHARGES, CAPACITANCES & GATE RES	SISTANCE						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 800 V		-	2943	-	pF
Output Capacitance	C <sub>OSS</sub>			_	258	-	
Reverse Transfer Capacitance	C <sub>RSS</sub>			-	24	-	
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = -5/20 \text{ V}, V_{DS} = 600 \text{ V},$ $I_{D} = 80 \text{ A}$ $f = 1 \text{ MHz}$		-	220	-	nC
Threshold Gate Charge	Q <sub>G(TH)</sub>			-	33	-	
Gate-to-Source Charge	$Q_{GS}$			_	66	-	
Gate-to-Drain Charge	$Q_{GD}$			-	63	-	
Gate-Resistance	R <sub>G</sub>			-	1.6	-	Ω
SWITCHING CHARACTERISTICS, VGS =	10 V						
Turn-On Delay Time	t <sub>d(ON)</sub>	$V_{GS} = -5/20 \text{ V}, V_{DS} =$	800 V,	-	21.6	35	ns
Rise Time	t <sub>r</sub>	$I_D = 80 \text{ A}, R_G = 2 \Omega$ Inductive load		-	21	34	
Turn-Off Delay Time	t <sub>d(OFF)</sub>	1		-	41	66	
Fall Time	t <sub>f</sub>	1		-	10	20	
Turn-On Switching Loss	E <sub>ON</sub>	1		-	494	-	μJ
Turn-Off Switching Loss	E <sub>OFF</sub>	-		-	397	-	
Total Switching Loss	E <sub>tot</sub>			_	891	-	
DRAIN-SOURCE DIODE CHARACTERIST		ı					
Continuous Drain-Source Diode Forward Current	I <sub>SD</sub>	$V_{GS} = -5 \text{ V}, T_J = 25^{\circ}\text{C}$	0	-	-	46	Α
Pulsed Drain–Source Diode Forward Current (Note 3)	I <sub>SDM</sub>			-	-	408	
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = -5 V, I <sub>SD</sub> = 30	A T 0500	_	3.7	_	V

Table 2. ELECTRICAL CHARACTERISTICS ( $T_J = 25^{\circ}C$  unless otherwise specified) (continued)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
DRAIN-SOURCE DIODE CHARACTERISTICS							
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = -5/20 \text{ V}, I_{SD} = 80 \text{ A},$ $dI_S/dt = 1000 \text{ A}/\mu\text{s}$	-	30	-	ns	
Reverse Recovery Charge	Q <sub>RR</sub>	di <sub>S</sub> /αt = 1000 A/μs	-	225	-	nC	
Reverse Recovery Energy	E <sub>REC</sub>		-	16	-	μJ	
Peak Reverse Recovery Current	I <sub>RRM</sub>		-	15	-	Α	
Charge Time	Ta	]	-	16	-	ns	
Discharge Time	Tb	7	_	15	-	ns	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### TYPICAL CHARACTERISTICS



ID, DRAIN CURRENT (A) 80 60 40  $T_J = 25^{\circ}C$ 20  $T_{J} = 175^{\circ}C$  $T_J = -55^{\circ}C$ 0 4 6 8 12 14 16 2 V<sub>GS</sub>, GATE-TO-SOURCE VOLTAGE (V)

Figure 5. Transfer Characteristics

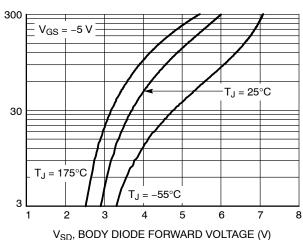


Figure 6. Diode Forward Voltage vs. Current

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## TYPICAL CHARACTERISTICS (continued)

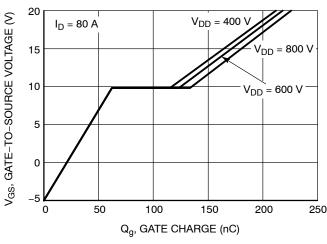


Figure 7. Gate-to-Source Voltage vs. Total Charge

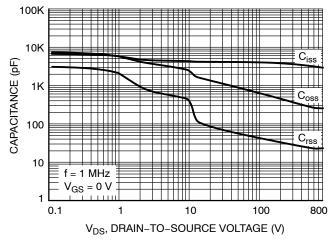


Figure 8. Capacitance vs. Drain-to-Source Voltage

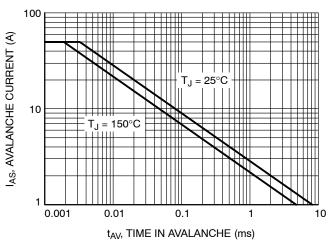


Figure 9. Unclamped Inductive Switching Capability

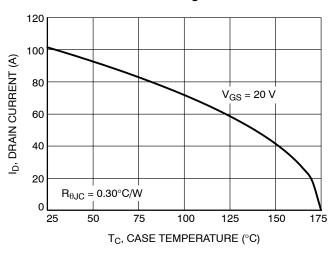


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

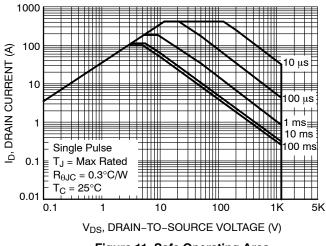


Figure 11. Safe Operating Area

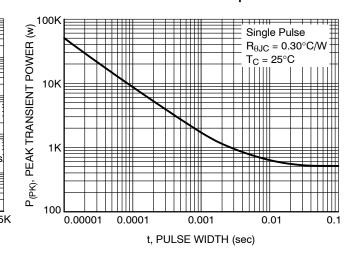


Figure 12. Single Pulse Maximum Power Dissipation

# TYPICAL CHARACTERISTICS (continued)

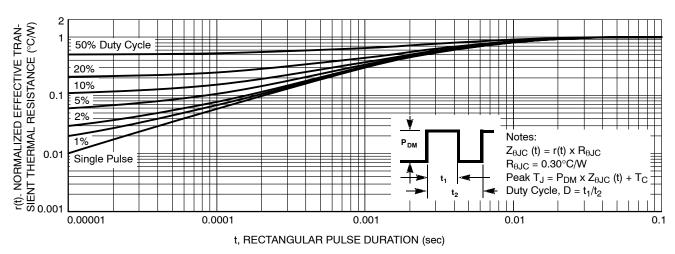
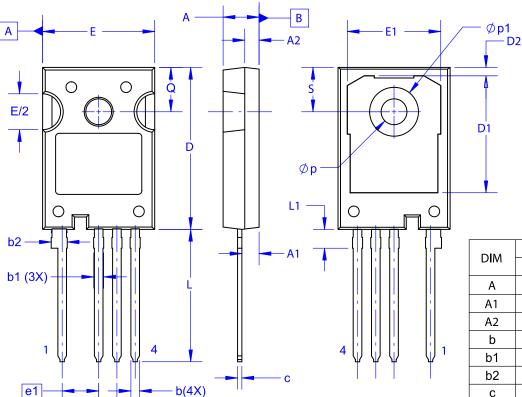


Figure 13. Junction-to-Ambient Thermal Response

## TO-247-4LD CASE 340CJ **ISSUE A**

**DATE 16 SEP 2019** 



#### NOTES:

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  D. DRAWING CONFORMS TO ASME Y14.5-2009.

DIM	MIN	NOM	MAX		
A	4.80	5.00	5.20		
A1	2.10	2.40	2.70		
A2	1.80	2.00	2.20		
b	1.07	1.20	1.33		
b1	1.20	1.40	1.60		
b2	2.02	2.22	2.42		
С	0.50	0.60	0.70		
D	22.34	22.54	22.74		
D1	16.00	16.25	16.50		
D2	0.97	1.17	1.37		
е	2.54 BSC				
e1	5.08 BSC				
E	15.40	15.60	15.80		
E1	12.80	13.00	13.20		
E/2	4.80	5.00	5.20		
L	18.22	18.42	18.62		
L1	2.42	2.62	2.82		
р	3.40	3.60	3.80		
p1	6.60	6.80	7.00		
Q	5.97	6.17	6.37		
S	5.97	6.17	6.37		

**MILLIMETERS** 

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